Dow SiLK™ Y 250 Semiconductor Dielectric Resin

Category : Polymer

Material Notes:

SiLK™ Y 250 has an average pore size of < 2nm and a range of 1-3 nm, porous SiLK™ resins enables continuous Tantulum PVD barriers for 65 nm technology and beyond. Information provided by Dow

Order this product through the following link:
http://www.lookpolymers.com/polymer_Dow-SiLK-Y-250-Semiconductor-Dielectric-Resin.php

Physical Properties	Metric	English	Comments
Density	0.930 g/cc	0.0336 lb/in³	
Thickness	0.220 - 0.310 microns	0.00866 - 0.0122 mil	

Thermal Properties	Metric	English	Comments
CTE, linear	49.0 µm/m-°C @Temperature 50.0 - 410 °C	27.2 µin/in-°F @Temperature 122 - 770 °F	
Decomposition Temperature	>= 500 °C	>= 932 °F	

Optical Properties	Metric	English	Comments
Refractive Index	1.53	1.53	

Electrical Properties	Metric	English	Comments
Dielectric Constant	2.2 @Frequency 100000 Hz	2.2 @Frequency 100000 Hz	
Dielectric Strength	>= 330 kV/mm	>= 8380 kV/in	

Descriptive Properties	Value	Comments
Leakage Current A/cm², max	0.00000002	0.5 MV/cm
Leakage Current A/cm², max	0.00000004	1.0 MV/cm

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